New Product Introduction July 2026

POWER

EasyPACK™ HD3 with TRENCHSTOP™ IGBT7 H7 for 300 kW+ utility-scaled solar inverter

EasyPACK™ S CoolSiC™ MOSFET 1200 V M2 and EasyPACK™ S 1200 V TRENCHSTOP™ IGBT T4

OptiMOS™ 8 power MOSFET 100 V

Automotive CoolSiC™ MOSFET 1700 V in D2PAK

CoolSiC™ MOSFET 750 V G2 in D2PAK 7pin, Q-DPAK TSC and TO247 4pin | automotive and industrial qualified

EasyPACK™ 1B CoolSiC™ Schottky diodes 650 V - OBC

Solid State Isolators ISSI20BxxF with integrated gate supply suitable for low-frequency, relay applications

TRENCHSTOP™ 1200 V IGBT7 S7 TO247

SENSOR TECHNOLOGY

XENSIV™ TLI49901 Hall-based linear position sensor

TRANSCEIVERS

TLE9351BVLE high-speed CAN transceiver for automotive and industrial HS CAN systems

EVALUATION BOARDS

REF_11KW_PFC_SIC_QD reference board 3L-ANPC bi-directional, top-side cooled converter

EVAL_2EDF7268G_HB dual channel isolated gate driver evaluation board for EiceDRIVER™ 2EDF7268G gate driver IC

LITIX™ LED platform animated exterior reference design

LITIX™ LED platform Arduino shield

EasyPACK™ HD3 with TRENCHSTOP™ IGBT7 H7 for 300 kW+ utility-scaled solar inverter

The new EasyPACK™ HD3 is a high-performance power modules package for next-gen PV/ESS string inverters, featuring 1200 V, up to 560 A, and state-of-the-art 3-level topologies. Utilizing TRENCHSTOP™ IGBT7 H7 and emitter controlled diodes, these robust EasyPACK™ modules deliver leading output power, efficiency, and reliability for utility-scale systems.

Features

- Easy family with baseplate for high power density and high voltage application
- High performance substrate and gel
- Flexible pin grid with high current solder/PressFit pin
- CTI 600 materials with high RTI
- Latest chip technologies

Benefits

- T_{vj} 175°C continuous
- Enable long-term thermal and mechanical stability
- Enable high power rating and density
- Support DC system up to 2000 V
- Low stray inductance design with high system efficiency

Competitive advantage

- Only single-module solution exceeding 400 kW in EasyPACK™ format
- Reliable single module solution for 300 kW+ string PV inverter
- Benchmark output power with leading-edge chip technology

Target applications

- Solar applications

Product collaterals/online support

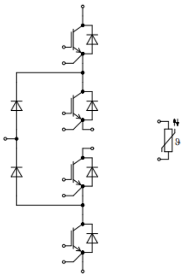
Product page: FC560R12D3H7FB78BPSA1

Product page: F3L420R12D3H7FBPSA1

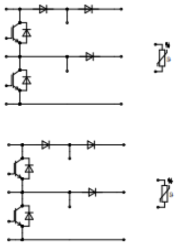
Product page: F3L420R12D3H7B78BPSA1

Block diagram

F3L420R12D3H7FBPSA1, F3L420R12D3H7B78BPSA1



FC560R12D3H7FB78BPSA1



Product overview incl. datasheet link

OPN	SP Number	Package
FC560R12D3H7FB78BPSA1	SP006233753	AG-EASYHD-711
F3L420R12D3H7FBPSA1	SP006098182	AG-EASYHD-711
F3L420R12D3H7B78BPSA1	SP006233749	AG-EASYHD-711

EasyPACK™ S CoolSiC™ MOSFET 1200 V M2 and EasyPACK™ S 1200 V TRENCHSTOP™ IGBT T4

Introducing EasyPACK™ S - smart, small, sizeable. The latest innovation in power electronics offers highest degree of automation in customer production line. With a compact 36x33x6 mm design, it enables system miniaturization and features robust thermal management, high reliability, and low EMI, making it a highly efficient solution for demanding applications and next-gen power electronics, empowering a new level of performance.

The FZ35R12ST4_H18_A is equipped with TRENCHSTOP™ IGBT7/4 and an emitter-controlled 7 diode and the FS25MR12SM2_A is equipped with the latest generation CoolSiC™ MOSFET 1200 V and high current press-fit pins.

Features

- \> High current press-fit pins
- \> Continuous operating temperature at 175°C
- \> Compact design
- \> Low thermal resistance
- \> Low switching losses

Benefits

- \> Very good pin-PCB connection
- \> Enhanced thermal performance
- \> Reduced assembly efforts
- \> Higher degree of freedom in terms of design

Competitive advantage

- \> Reduced system costs and high system reliability

Target applications

- \> On-board charger
- \> PTC heater
- \> EV charging
- \> HVAC/heat pump
- \> Servo drives

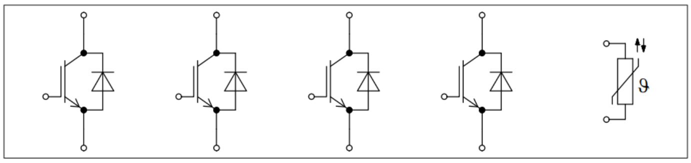
Product collaterals/online support

[Product page: FZ35R12ST4H18ABPSA1]

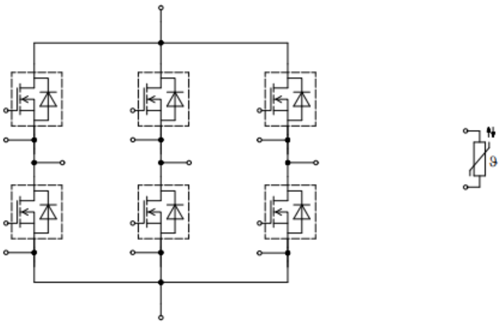
[Product page: FS25MR12SM2ABPSA1]

Block diagram

FZ35R12ST4H18ABPSA1t



FS25MR12SM2ABPSA1



Product overview incl. datasheet link

OPN	SP Number	Package
FZ35R12ST4H18ABPSA1	SP006080590	AG-EASYS-721
FS25MR12SM2ABPSA1	SP006080618	AG-EASYS-3221

Classification: Restricted document! The information presented is valid from July 1st 2026. Please check the latest Distribution Price Book for current prices and minimum quantities.

OptiMOS™ 8 power MOSFET 100 V

The new OptiMOS™ 8 power MOSFET 100 V technology, designed to address various motor control and battery protection applications with the need for lowest conduction losses. With industry's lowest $R_{DS(on)}$ and excellent switching behavior, OptiMOS™ 8 100 V enables unmatched power density, system cost savings compared to its predecessor OptiMOS™ 5, all while maintaining next-level capabilities and an outstanding price-to-performance ratio.

Features

- N-channel, normal level
- Very low on-resistance $R_{DS(on)}$
- High I_D current rating
- Tight $V_{GS(th)}$ spread
- Soft body diode recovery and low Q_{rr}
- 100% avalanche tested
- Pb-free lead plating; RoHS compliant
- Halogen-free according to IEC61249-2-21
- MSL 1 classified according to J-STD-020

Benefits

- Lowest conduction losses through very low on-resistance $R_{DS(on)}$ resulting in higher peak and steady-state current capability
- Improved current sharing due to tight $V_{GS(th)}$ spread
- Excellent EMI behavior due to soft body diode
- Ease of use

Competitive advantage

- Price/performance optimized
- Efficient power handling
- Power density
- High reliability

Target applications

- Drives
- Battery management
- Server
- Telecom

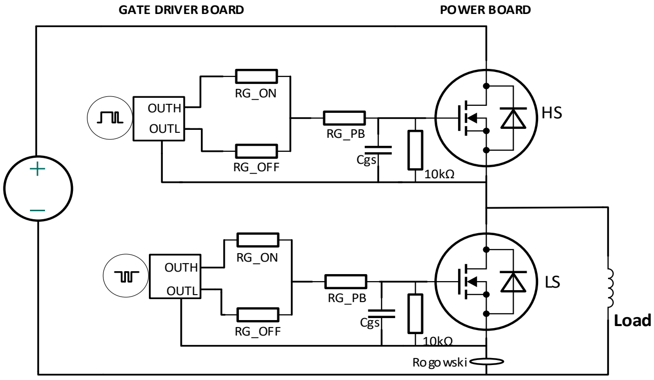
Product collaterals/online support

[Product family page]

[Product page]

Block diagram

48 V servo drive



Product overview incl. datasheet link

OPN	SP Number	Package
IPF019N10NM8ATMA1	SP006114981	PG-TO263-7

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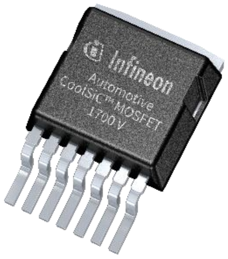
Automotive CoolSiC™ MOSFET 1700 V in D2PAK

The new Automotive CoolSiC™ 1700 V D2PAK portfolio empowers next-generation EV architectures with higher power density, reduced system cost, and increased switching efficiency. Designed for the latest flyback converter topologies, it enables smaller and more performant auxiliary power supplies and µDCDC converters, helping customers accelerate their shift toward more efficient high-voltage designs.



Features

- Optimized for flyback converters
- Automotive grade reliability
- Scalable portfolio

Benefits

- Lower system cost
- Higher power density
- Lower switching losses

Competitive advantage

- Smaller SMD package vs. TO247 competition enabling lower system cost and higher power density

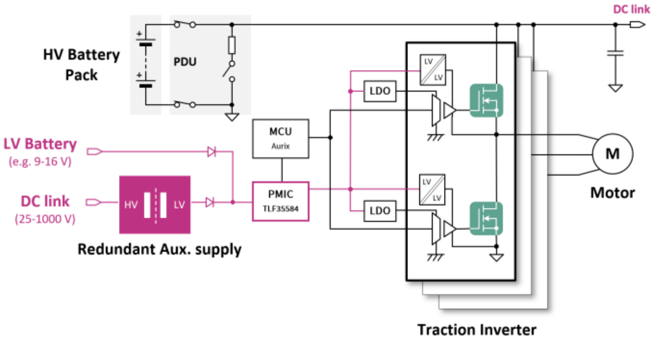
Target applications

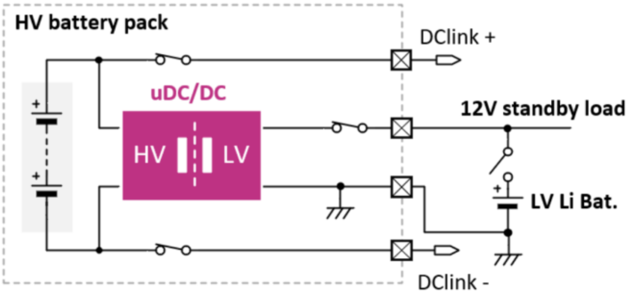
- Auxiliary power supply
- HV-LV DCDC converters

Product collaterals/online support

[Product family page]

Block diagram





Product overview incl. datasheet link

OPN	SP Number	Package
[AIMBF170R1K0M1XTMA1]	SP006043734	PG-TO263-7
[AIMBF170R650M1XTMA1]	SP006043730	PG-TO263-7
[AIMBF170R450M1XTMA1]	SP006043738	PG-TO263-7

CoolSiC™ MOSFET 750 V G2 in D2PAK 7pin, Q-DPAK TSC and TO247 4pin | automotive and industrial qualified

The CoolSiC™ MOSFET 750 V G2 delivers outstanding efficiency, reliability and power density for next-generation designs. With enhanced robustness, ultra-low switching losses and optimized capacitance, it enables higher frequencies and compact systems. Perfect for EV charging solar, AI servers and industrial power applications demanding maximum performance.

Features

- 100% avalanche tested
- Best in class $R_{DS(on)}$ x Q_{fr}
- Excellent $R_{DS(on)}$ x Q_{oss} and $R_{DS(on)}$ x Q_G
- Unique low C_{rss}/C_{iss} and high $V_{GS(th)}$
- Improved package interconnect with .XT
- Driver source pin available

Benefits

- Enhanced robustness and reliability
- Superior efficiency in hard switching
- Higher switching frequency
- Robustness against parasitic turn on
- Best in class thermal dissipation
- Reduced switching losses

Competitive advantage

- 100% avalanche tested switches for automotive and industrial applications
- Extended negative gate driving voltage (-7 V to -11 V)
- Enhanced thermal performance (up to 200°C)
- Figure-of-Merits improved by 20-35% over the previous generation
- High $V_{GS(th)}$ + low C_{rss}/C_{iss} = 0 V switch off
- JEDEC-qualified top-side cooled package for higher power density

Target applications

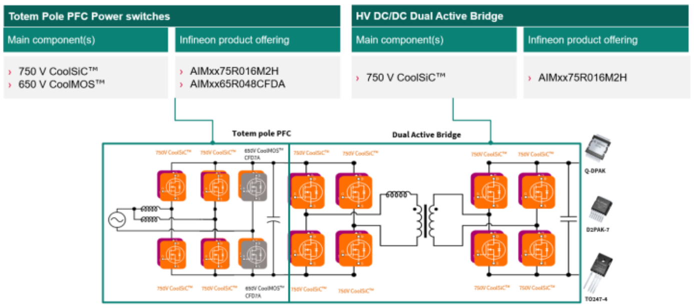
- Solid state relays and isolators
- Solid-state circuit breaker
- EV charging
- Photovoltaic
- Uninterruptible power supplies (UPS)
- Energy storage systems
- Battery formation
- AC-DC power conversion for telecom infrastructure
- Server power supply units (PSU)
- Automotive applications
- HV LV DC-DC converters
- On-board chargers
- Circuit breakers (HV battery disconnect switch, DC and AC low frequency switch, HV eFuse)

Product collaterals/online support

[Product family page]()

Block diagram

Application example: OBC:PFC and DC-DC stages



Totem Pole PFC Power switches	
Main component(s)	Infineon product offering
750 V CoolSiC™ 650 V CoolMOS™	AIMxx75R016M2H AIMxx65R048CFDA

HV DC/DC Dual Active Bridge	
Main component(s)	Infineon product offering
750 V CoolSiC™	AIMxx75R016M2H

Product overview incl. datasheet link in the next page

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OPN	SP Number	Package
AIMBG75R007M2HXTMA1	SP006087222	PG-TO263-7
AIMBG75R020M2HXTMA1	SP006087213	PG-TO263-7
AIMBG75R025M2HXTMA1	SP006087210	PG-TO263-7
AIMBG75R033M2HXTMA1	SP006087207	PG-TO263-7
AIMBG75R040M2HXTMA1	SP006087204	PG-TO263-7
AIMBG75R050M2HXTMA1	SP006087201	PG-TO263-7
AIMBG75R060M2HXTMA1	SP006083709	PG-TO263-7
AIMDQ75R004M2HXTMA1	SP005982743	PG-HDSOP-22
AIMDQ75R007M2HXTMA1	SP005982740	PG-HDSOP-22
AIMDQ75R011M2HXTMA1	SP006089226	PG-HDSOP-22
AIMDQ75R020M2HXTMA1	SP006089223	PG-HDSOP-22
AIMDQ75R033M2HXTMA1	SP006089220	PG-HDSOP-22
AIMDQ75R040M2HXTMA1	SP006089213	PG-HDSOP-22
AIMDQ75R050M2HXTMA1	SP006089210	PG-HDSOP-22
AIMZA75R007M2HXKSA1	SP006113236	PG-TO247-4
AIMZA75R011M2HXKSA1	SP006113233	PG-TO247-4
AIMZA75R016M2HXKSA1	SP006113285	PG-TO247-4
AIMZA75R020M2HXKSA1	SP006113282	PG-TO247-4
AIMZA75R025M2HXKSA1	SP006113279	PG-TO247-4
AIMZA75R033M2HXKSA1	SP006113276	PG-TO247-4
AIMZA75R040M2HXKSA1	SP006113273	PG-TO247-4
AIMZA75R050M2HXKSA1	SP006113270	PG-TO247-4
AIMZA75R060M2HXKSA1	SP006113239	PG-TO247-4
IMBG75R007M2HXTMA1	SP006098953	PG-TO263-7
IMBG75R011M2HXTMA1	SP006098950	PG-TO263-7
IMBG75R016M2HXTMA1	SP006098947	PG-TO263-7
IMBG75R020M2HXTMA1	SP006098942	PG-TO263-7
IMBG75R025M2HXTMA1	SP006098939	PG-TO263-7
IMBG75R033M2HXTMA1	SP006098936	PG-TO263-7
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IMDQ75R020M2HXTMA1	SP006089243	PG-HDSOP-22
IMDQ75R033M2HXTMA1	SP006089240	PG-HDSOP-22
IMDQ75R040M2HXTMA1	SP006089237	PG-HDSOP-22
IMDQ75R050M2HXTMA1	SP006089229	PG-HDSOP-22
IMZA75R007M2HXKSA1	SP006113380	PG-TO247-4
IMZA75R011M2HXKSA1	SP006113377	PG-TO247-4
IMZA75R016M2HXKSA1	SP006113421	PG-TO247-4
IMZA75R020M2HXKSA1	SP006113418	PG-TO247-4
IMZA75R025M2HXKSA1	SP006113415	PG-TO247-4
IMZA75R033M2HXKSA1	SP006113398	PG-TO247-4
IMZA75R040M2HXKSA1	SP006113390	PG-TO247-4
IMZA75R050M2HXKSA1	SP006113386	PG-TO247-4
IMZA75R060M2HXKSA1	SP006113383	PG-TO247-4

EasyPACK™ 1B CoolSiC™ Schottky diodes 650 V - OBC

AQG324-qualified EasyPACK™ integrates the advanced capabilities of the CoolMOS™ CFD7A 650 V, offering an ideal balance of cost and performance for on-board charger and EV auxiliary applications

Typical appearance

Features

> Highly reliable press-fit pins
> Pre-applied thermal interface material
> Enables compact design
> Integration of SMD possible

Benefits

> Very good pin-PCB connection
> Better thermal performance
> Reduced assembly efforts
> Higher degree of freedom in terms of design

Competitive advantage

> Reduced system costs and high system reliability

Target applications

> DC charger for EV
> On-board charger

Product collaterals/online support

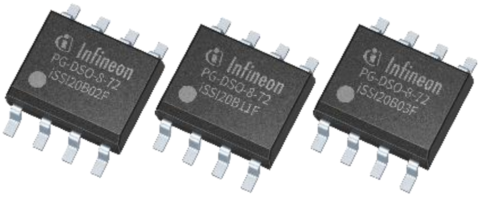
Product page

Product overview incl. datasheet link

OPN	SP Number	Package
FZ35R12W1T4B18ABPSA1	SP005740418	AG-EASY1B-721

Solid State Isolators ISSI20BxxF with integrated gate supply suitable for low-frequency, relay applications

Infineon's Solid State Isolators (SSIs) transfer signal and energy across the isolation barrier using a coreless transformer, so no isolated output supply is needed. Suitable for low-frequency relay applications, they provide higher output drive capability than Photovoltaic Isolators (PVIs) and greater reliability than Electromechanical Relays (EMRs). Integrated protection features combined with an external switch enable safe, easy solid-state relay designs.



Features

- Higher reliability than Electromechanical Relays (EMRs)
- Higher output current than Photovoltaic Isolators (PVIs)
- Fast turn-off on fault detection
- Integrated protection features: Over-current Protection (OCP), Over-temperature protection (OTP) and Dynamic Miller clamping (DMC)
- UL1577

Benefits

- No isolated output gate supply required
- Lower power dissipation leads to elimination of heat sink
- High system reliability, low maintenance costs
- Compact solution

Competitive advantage

- Significantly higher output current than PVIs
- Competitive footprint and pricing v/s PVIs
- Integrated OCP, OTP, DMC - no external components
- Zero-voltage turn-on via external circuitry
- Fault status feedback via external circuitry
- Drives latest Si, SiC, SiC-JFET, MV BDS GaN switches
- Higher reliability v/s EMR - over 1,000,000 switching cycles

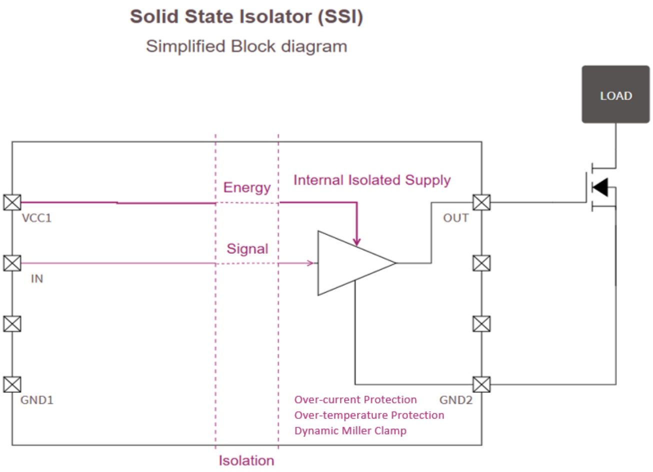
Target applications

- BMS - battery disconnect in AI BBU, ESS, LEV, etc.
- Low voltage building automation
- Solid State Relay (SSR) modules
- Industrial automation
- Programmable Logic Controllers (PLC)
- Digital input/output (I/O) modules
- Laboratory power supplies
- Telecommunications infrastructure
- Test and measurement systems

Product collaterals/online support

Product family page

Block diagram

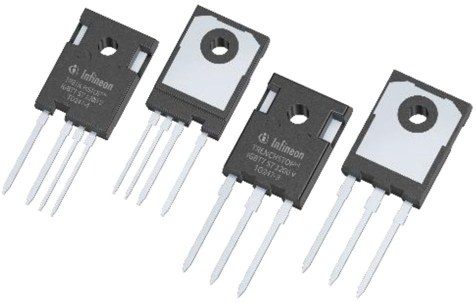


Product overview incl. datasheet link

OPN	SP Number	Package
ISSI20B02FXUMA1	SP006149805	PG-DSO-8
ISSI20B03FXUMA1	SP006149807	PG-DSO-8
ISSI20B11FXUMA1	SP006149809	PG-DSO-8

TRENCHSTOP™ 1200 V IGBT7 S7 TO247

This automotive grade IGBT delivers high efficiency with low $V_{CE(sat)}$ even at 175 °C, ensuring reliable operation in demanding environments. Its wide dv/dt controllability and robust short circuit capability enable flexible and safe system design. The TO247 package with integrated diode supports easy integration, high creepage and compact, high power density designs optimized for low to mid frequency applications.



Features

- Low saturation voltage $V_{CE(sat)}$ = 2.0 V at T_{vj} = 175 °C
- Wide range of dv/dt controllability
- 4 µsec short circuit robustness and humidity robustness
- IGBT with diode
- Higher pulse current 3xInom capability
- Very good performance at low - mid switching frequency range (8-16 kHz)

Benefits

- The best-in-class MPT technology of IGBT7 S7 allows reduction of both $V_{CE(sat)}$ by ~ 10% and total switching losses up to 30% lower than previous generations

Competitive advantage

- Simple and lower cost gate driver circuit design
- Improved thermal performance and reduced cooling efforts
- Easier assembly and reduced system cost through high creepage distance
- 4 versions (15 A to 50 A) to address exact customer requirements

Target applications

- High voltage auxiliary drive applications
- HV heater
- 800 V OBC

Product collaterals/online support

Product family page

Product overview incl. datasheet link

OPN	SP Number	Package
AIKWH15N120CS7XKSA1	SP006111113	PG-TO247-3
AIKWH25N120CS7XKSA1	SP006111117	PG-TO247-3
AIKWH40N120CS7XKSA1	SP006111121	PG-TO247-3
AIKWH50N120CS7XKSA1	SP006111125	PG-TO247-3
AIKZH15N120CS7XKSA1	SP006111129	PG-TO247-4
AIKZH25N120CS7XKSA1	SP006111133	PG-TO247-4
AIKZH40N120CS7XKSA1	SP006111137	PG-TO247-4
AIKZH50N120CS7XKSA1	SP006111141	PG-TO247-4

XENSIV™ TLI49901 Hall-based linear position sensor

XENSIV™ TLx49901 Linear Hall-Effect Sensor ICs with analog output in 3-pin SOT23 package incorporate low-noise performance with a large signal bandwidth up to 20 kHz. The power supply voltage range from 3.3 V to 5.5 V enables usage in a wide range of applications, including battery-powered devices. The sensors are available in industrial (TLI) and automotive (TLE) versions.

Features

- Analog ratiometric linear hall sensor
- 3.3 V and 5 V nominal supply
- Wide temperature range: -40°C to 125°C/150°C
- Best-in-class magnetic accuracy
- High linearity
- Lowest sensitivity drift error over lifetime and temperature range
- Standard SOT23-3 package
- Qualified for automotive and industrial applications

Benefits

- Accurate magnetic field measurement for precise position feedback
- Value-optimized linear hall sensor for flexible designs
- Low drift performance
- Good fit for trigger use cases like in power tools, game controller and key switches
- Ideal in extreme operating conditions

Competitive advantage

- Best-in-class magnetic accuracy
- Higher linearity (<± 0.5% max error)
- Low drift over lifetime and temperature (±5-±8%)

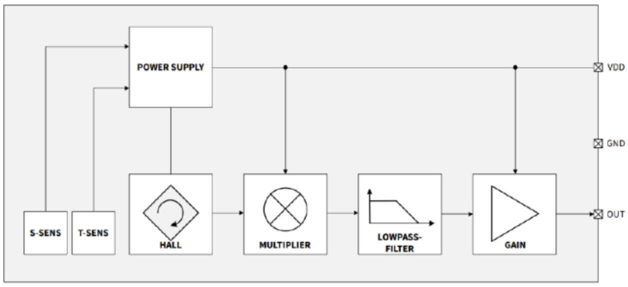
Target applications

- HMI controls (knob, trigger, button, slider)
- Pedal and valve position sensing
- Game controller joysticks and triggers
- Linear and angle sensing
- Automotive door module
- Two-wheeler throttle, side bar, brake lever

Product collaterals/online support

Product family page

Block diagram



Product overview incl. datasheet link

OPN	SP Number	Package
TLE499011MXTMA1	SP006041489	PG-SOT23-3
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TLE499013MXTMA1	SP006041506	PG-SOT23-3
TLE499014MXTMA1	SP006041510	PG-SOT23-3
TLI499011MXTMA1	SP006041535	PG-SOT23-3
TLI499012MXTMA1	SP006041539	PG-SOT23-3
TLI499013MXTMA1	SP006041544	PG-SOT23-3
TLI499014MXTMA1	SP006041548	PG-SOT23-3

TLE9351BVLE high-speed CAN transceiver for automotive and industrial HS CAN systems

The TLE9351BVLE is a high-speed CAN transceiver for automotive and industrial HS CAN systems, compliant with ISO 11898 2:2024 and supporting CAN FD up to 5 Mbit/s. It provides strong protection against interference with high ESD robustness and low electromagnetic emissions, often removing the need for external protection or filtering. The device also features low power standby with bus wake up capability and integrated safety functions like overtemperature protection and current limiting.

Features

> Excellent ESD robustness. Bus ESD robustness improved up to ±10 V
> Lower CAN bus leakage current in power-down state
> Lower electromagnetic emission (EME) allows the use without additional common mode choke
> Wide compatibility - five TLE935xBx devices replace up to 25 predecessors
> Compact footprint (3x3 mm)

Benefits

> Better ESD immunity on wiring without extra component
> Higher system efficiency
> High volume cost saving on common mode choke (CMC)
> Easy transition for new projects. Full HW and SW compatibility with 1MBit/s, 2MBit/s and 5MBit/s CAN devices
> Saves PCB area/smaller footprint

Competitive advantage

> Excellent ESD robustness. Bus ESD robustness improved up-to ±10 V
> Reduced design complexity and external components

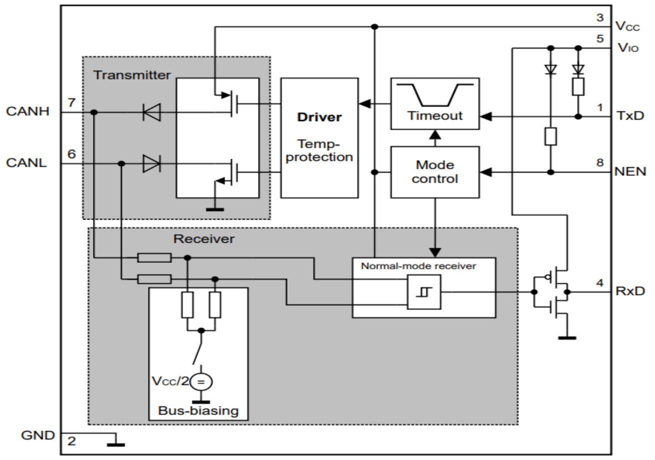
Target applications

> Engine management
> Transmission
> Electric power steering
> Central gateway

Product collaterals/online support

[Product page]

Block diagram



Product overview incl. application notes link

OPN	SP Number	Package
TLE9351BVLEXUMA1	SP006133581	PG-TSON-8

REF_11KW_PFC_SIC_QD reference board 3L-ANPC bi-directional, top-side cooled converter

This reference board represents a newly developed multilevel active-neutral-point-clamped (ANPC) bi-directional converter for multiple applications with both 3-phase and 1-phase AC and 800 V DC and power ratings of 11 kW and 7.3 kW. This board works with high efficiency (99.15% peak) and high-power density (> 11kW/L) enabled by Infineon's newest 750 V CoolSiC™ and 600 V CoolMOS™ in Q-DPAK package.

Features

- Three-phase design (3L-ANPC)
- Multi-level power conversion
- High performance (efficiency and power density)
- Bi-directional capability
- Full digital control
- 600 V/750 V Si/SiC MOSFETs in Q-DPAK TSC

Benefits

- Addressing a wide range of applications
- Multiple cooling possibilities
- Compact form factor

Competitive advantage

- The demonstrated system solution achieves premium power density and efficiency by introducing multi-level topology and lower voltage rating power semiconductors with better figure-of-merit into the system
- The use of 600 – 750 V power semiconductors in the 800 VDC based system makes it possible to switch at a frequency of 65 kHz, reducing the size of magnetics, boosting the efficiency and increasing the power density

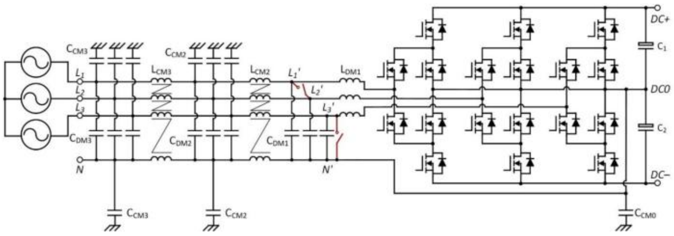
Target applications

- Battery energy storage systems (BESS)
- EV charging
- On-board charger (OBC)
- Industrial power supplies

Product collaterals/online support

Board page

Block diagram



Product overview incl. application notes link

OPN	SP Number	Package
REF11KWPFCSICQDTOBO1	SP006136499	LG-MADK-1

EVAL_2EDF7268G_HB dual channel isolated gate driver evaluation board for EiceDRIVER™ 2EDF7268G gate driver IC

The EVAL_2EDF7268G_HB evaluation board is designed to be used by engineers to evaluate the 2EDF7268G EiceDRIVER™ isolated gate driver ICs and discrete power switches from Infineon in a half-bridge configuration. The generic half-bridge topology is configurable for boost or buck operation, double-pulse testing or continuous PWM operation at full power.

Features

- Infineon BSC600N25NS3 G 250 V OptiMOS™ N-channel MOSFETs in PG-TDSON-8-1 in a half-bridge configuration
    - UVLO supporting all gate driver supply voltages
    - Test points for monitoring critical signal
    - In default configuration (non-isolated), a single external power supply is used to supply the input side as well as the output side of the gate driver. It can also be configured to have an independent isolated power supply for input and output side of the gate driver

Benefits

- PCB layout designed to ensure optimal switching performance of the half-bridge
- Easy evaluation of 2EDF7268G and accompanying switches

Competitive advantage

- Easy system evaluation

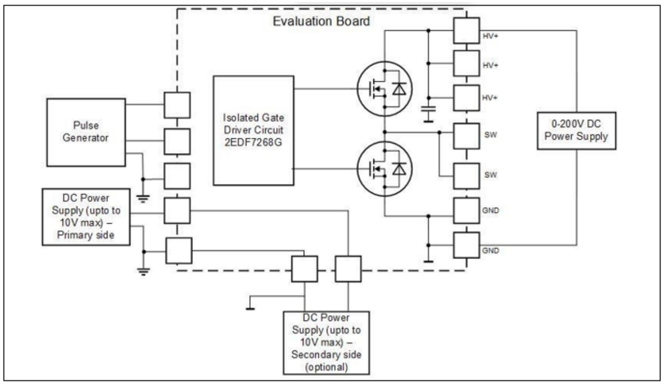
Target applications

- DC-DC power conversion for telecommunications infrastructure
- Microinverter solutions
- Power optimizer solutions
- Industrial power supplies
- Power tools
- Low-voltage drives

Product collaterals/online support

Board page

Block diagram



Product overview incl. user guide link

OPN	SP Number	Package
EVAL2EDF7268GHBTOBO1	SP006195963	LG-MADK-1

LITIX™ LED platform animated exterior reference design

The REF_LEDP_ANI_EXT is a reference design developed for automotive animated exterior lighting application. This reference design serves as a reference for thermal performance and electrical design, optimized in BOM and PCB size. In a complete system offering, REF_LEDP_ANI_EXT is used alongside LITIX™ SHIELD_LED_PLATFORM Arduino Shield, Traveo™ II Starter Kit, and uIO-Stick V2.

Features

- Six TLD7002-16ES with pre-written OTP
- 84 Pure Green LEDs
- Individually addressable LEDs
- Example software included
- OTP configuration included

Benefits

- Quick evaluation
- Efficient development

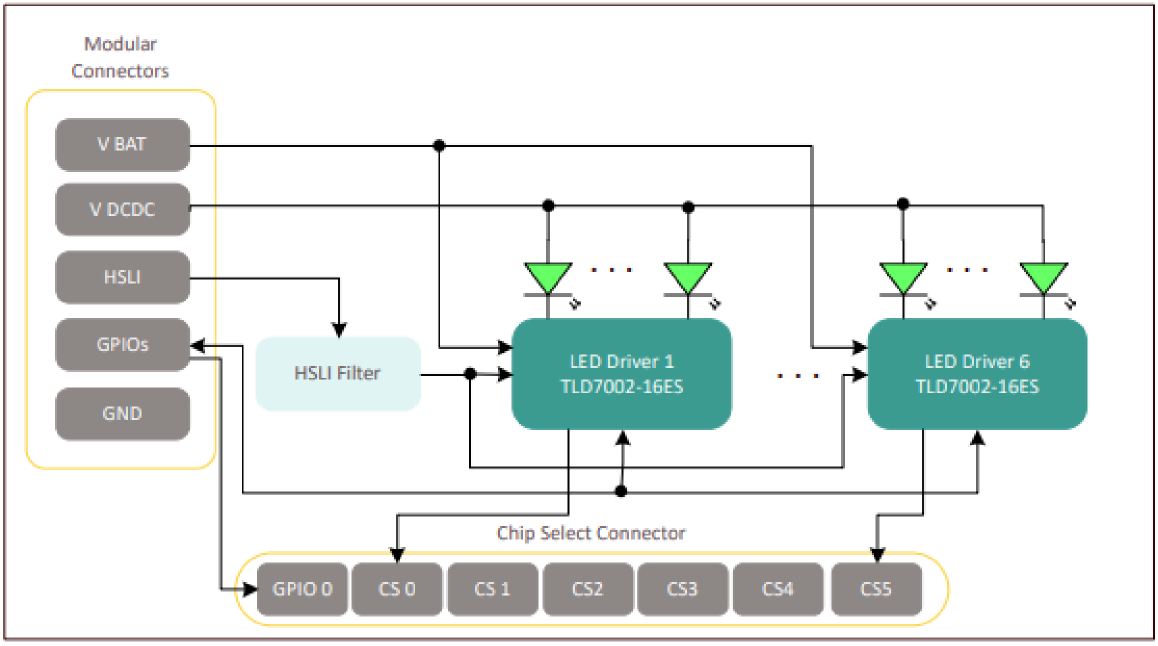
Product collaterals/online support

Reference design page

Target applications

- Automotive animated exterior lighting

Block diagram



Product overview incl. user guide link

OPN	SP Number	Package
REFLEDPANIEXTTOBO1	SP006183338	LG-MADK-1

LITIX™ LED platform Arduino shield

The SHIELD_LED_PLATFORM is an Arduino shield that supplies the LED Platform reference designs and enables communication between the Traveo II Starter Kit or the uIO-Stick v2 and the LED Platform reference designs. In a complete system offering, SHIELD_LED_PLATFORM is used alongside LITIX™ REF_LEDP_ANI_EXT Animated Exterior reference design, Traveo™ II Starter Kit, and uIO-Stick V2.

Features

- Reverse Polarity Protection
- Compatible with Traveo II Starter Kit
- Compatible with uIO-Stick v2

Benefits

- Easy evaluation
- High compatibility

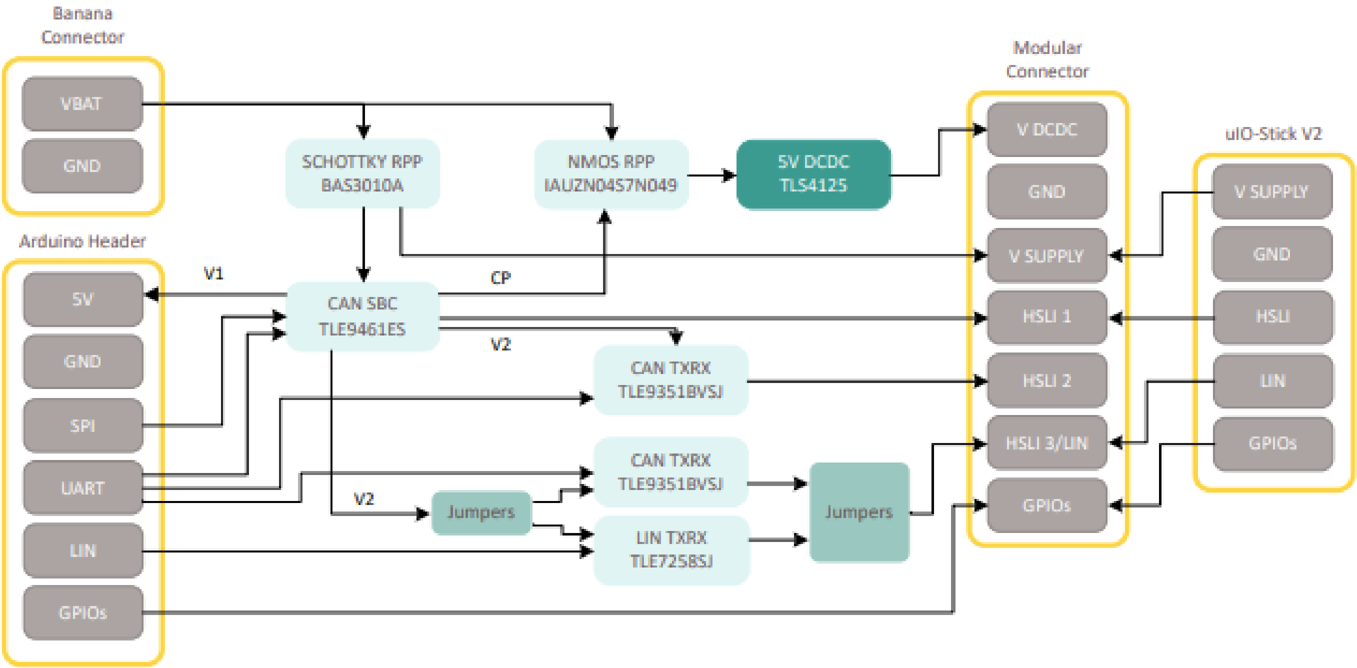
Product collaterals/online support

[Reference design page]()

Target applications

- Automotive animated exterior lighting

Block diagram



Product overview incl. user guide link

OPN	SP Number	Package
[SHIELDLEDPLATFORMTOBO1]()	SP006183342	LG-MADK-1